REMARKS/ARGUMENTS

Reconsideration of the application is requested.

Claims 7 and 20-31 remain in the application. Claim 20 has been amended. Claims 1-6 and 8-19 have been cancelled.

In the second paragraph on page 2 and the paragraph bridging pages 2 and 3 of the above-identified Office action, claims 7 and 20-31 have been rejected under 35 U.S.C. § 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

More specifically, the Examiner has stated that the exact meaning of the word "areally" is still not clear. As already discussed in detail in the response to the previous Office action, the word "arealy" stems from the word "area" and "arealy over" means over a certain extent of a surface area. The meaning of the word "areally" is therefore believed to be clear. Nevertheless, the language of claim 20 has been amended to facilitate the prosecution. The amended claim 20 now clearly recites that the solar cell (30) is disposed

entirely over an area of the surface of the semiconductor wafer (10) and over the top surfaces of the semiconductor chips (1) (see Fig. 5A).

With regard to the radiation-absorbing material, it is noted that the material is not claimed in the claims and is not part of the invention. In addition, Applicants still believe that one skilled in that art dealing with the manufacturing of semiconductor devices, i.e. dealing with lithography processes, should be aware of appropriate materials for forming a layer which is appropriate to absorb radiation. It is to be noted that the thickness of the layer of any absorbing material (for example, a kind of well known material used for absorbing solar radiation for heating water) may also be varied to a sufficient amount to gain a radiation-absorbing layer.

With regard to the Examiner's comment that the wafer is like a piece of plastic with coins embedded in the plastic, please refer to Applicants' remarks presented in the response to the previous Office action. As can be seen from Fig. 4, scribe lines (11) are disposed between the semiconductor chips (1) and divide the chips from one another. The scribe lines have a surface lower than the top surface of the chips. Therefore, the cross-sectional views of Figs. 5A and 5B are correct. It

is noted that the chips are not entirely buried in the wafer. In other words, the top surface of the chips is above the surface of the wafer. Moreover, Figs. 5A and 5B only show diagrammatic cross-sectional views illustrating the principal arrangement of the wafer, the chips, the scribe lines dividing the chips from each other, and the solar cell. A person skilled in the art should be able to transform these illustrations into a real application.

It is accordingly believed that the claims meet the requirements of 35 U.S.C. § 112, first paragraph. Should the Examiner find any further objectionable items, counsel would appreciate a telephone call during which the matter may be resolved. The above-noted changes to the claims are provided solely for cosmetic and/or clarificatory reasons. The changes are neither provided for overcoming the prior art nor do they narrow the scope of the claims for any reason related to the statutory requirements for a patent.

In the paragraph bridging pages 3 and 4 of the above-mentioned Office action, claims 20, 23, and 27 have been rejected as being anticipated by Cook et al. (US Pat. No. 6,300,785 B1) under 35 U.S.C. § 102(b).

As will be explained below, it is believed that the claims were patentable over the cited art in their original form and the claims have, therefore, not been amended to overcome the references. However, the language of claim 20 has been slightly modified in an effort to even more clearly define the invention of the instant application, as discussed above.

Before discussing the prior art in detail, it is believed that a brief review of the invention as claimed, would be helpful.

Claim 20 calls for, inter alia:

> an energy source disposed above said semiconductor wafer and connected to said semiconductor chip for providing an electrical energy supply to said semiconductor chip, said energy source having at least one solar cell for generating an operating current for said semiconductor chip by optical radiation fed in contactlessly, said solar cell being disposed entirely over said area of said surface of said semiconductor wafer and over said top surfaces of said semiconductor chips. (Emphasis added.)

According to the invention of the instant application, the solar cell (30) is disposed over the semiconductor wafer (10) and the semiconductor chips (1) (see Fig. 5A). In contrast, in Cook et al. the solar cells are disposed in the scribe lines or kerfs.

Clearly, Cook et al. do not show "said solar cell being disposed entirely over said area of said surface of said

semiconductor wafer and over said top surfaces of said semiconductor chips", as recited in claim 20 of the instant application.

Claim 20 is, therefore, believed to be patentable over the art and since all of the dependent claims are ultimately dependent on claim 20, they are believed to be patentable as well.

In view of the foregoing, reconsideration and allowance of claims 7 and 20-31 are solicited.

In the event the Examiner should still find any of the claims to be unpatentable, counsel would appreciate a telephone call so that, if possible, patentable language can be worked out. In the alternative, the entry of the amendment is requested as it is believed to place the application in better condition for appeal, without requiring extension of the field of search.

If an extension of time for this paper is required, petition for extension is herewith made. Please charge any fees which might be due with respect to 37 CFR Sections 1.16 and 1.17 to

the Deposit Account of Lerner and Greenberg, P.A., No. 12-1099.

Respectfully submitted,

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For Applicants

YC

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